## WHAT IS CLAIMED IS:

1.

	comprising		
5		an extrinsic base, and	
		a lateral trench beneath the extrinsic base.	
	2.	A BJT of claim 1, wherein the trench is filled with air.	
	3.	A BJT of claim 1, wherein the trench is filled with an insulator.	
	4.	A BJT of claim 3, wherein the insulator is a high step coverable	
10		insulating material.	
	5.	A BJT of claim 4 wherein the insulator is PETEOS.	
	6.	A BJT of claim 1, wherein the trench has a <110> orientation.	
	7.	A BJT of claim 6, wherein the trench is formed in a <100> silicon	
	wafe	r.	
15	8.	A method of forming a laterally extending trench in a semiconductor	
	mate	rial underneath an extrinsic base of a BJT, comprising	
		choosing a predetermined crystal orientation,	
		etching a vertically extending STI region next to the extrinsic	
		base, and	
20		using an anisotropic etchant to etch the laterally extending	
		trench to extend laterally from the STI.	
	9.	A method of claim 8, wherein choosing the crystal orientation includes	
	choo	sing a wafer with a <100> orientation.	
	10.	A method of claim 8, wherein the choosing of the crystal orientation	
25	includes choosing a lateral trench direction that is in the <110> direction.		
	11.	A method of claim 10, wherein the semiconductor material is silicon.	
	12.	A method of claim 11, wherein the etchant is a wet anisotropic silicon	
	etcha	etchant.	
	13.	A method of claim 12, wherein the etchant includes KOH.	

A bipolar transistor (BJT) with reduced base-collector capacitance

- 14. A method of claim 13, wherein the etchant further includes alcohol and water.
- 15. A method of claim 12, wherein the etchant includes TMAH.